Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L60	1	"324"/$ and strip with (die dice) with ((locat$4 position) and ((database data adj base) (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:36
L59	35	"324"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:36
L48	10	"700"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:33
L57	5	strip with (die dice) same ((locat$4 position) and ((database data adj base) and (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:37
L56	9	strip with (die dice) with ((locat$4 position) and ((database data adj base) (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:37
L47	2157	strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:06
L55	141	"257"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L54	24	"235"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L53	278	"156"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L52	79	"438"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02

L51	0	"716"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L50	0	"714"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L49	3	"702"/$ and strip with (die dice) with ((locat$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L45	5	strip with (die dice) same ((locat$4 position) and (database data adj base) and (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:01
L44	9	strip with (die dice) same ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:52
L43	20	strip same (die dice) same ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:39
L42	5	strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:37
L41	4	(camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:36
L40	3	"438"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:35
L39	2	"257"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34

L38	0	"235"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L37	3	"156"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L36	0	"716"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L35	0	"702"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L34	1	"700"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L33	0	"714"/$ and (camera vision) and strip with (die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L28	2	"714"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:33
L32	5	"235"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L31	4	"257"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L30	6	"156"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32

L29	3	"716"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L27	5	"702"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L26	4	"700"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L25	16	"438"/$ and (camera vision) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L24	3	"438"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L23	2	"257"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L21	3	"156"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L22	0	"235"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L20	0	"716"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L19	0	"714"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30

L18	0	"702"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L17	1	"700"/$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:29
L16	19	(camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:28
L15	15	(camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:28
L14	4	wafer with strip with (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L13	0	wafer with strip with (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L11	0	(camera vision) and wafer with strip with (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L12	4	(camera vision) and wafer with strip with (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:16
L10	51	(camera vision) and wafer with (strip die dice) and (strip die dice) with ((locat$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:15

L9	53	(camera vision) and wafer same (strip die dice) and (strip die dice) with ((locat$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:13
L8	138	wafer same (strip die dice) and (strip die dice) with ((locat$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:12
L7	17	wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:03
L6	21	wafer same strip same (die dice) and (strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:50
L5	34	wafer same strip same (die dice) and (wafer strip die dice) with ((locat$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:43
L4	56	wafer same strip same die and (locat$4 position) and (database data adj base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:23
L3	605	wafer and strip and die and (locat$4 position) and (database data adj base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:21

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6049624 65
6226394 65
6226394 65
6400840 65
6730532 65
6730545 65
6901984 65
6931298 65
5549716 54
5726920 54
6100590 54
5220724 54
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5981971 54
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5675127 54
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5824964 54
5838023 54
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5933713 54
5956838 54
5960260 54
6008061 54
6014018 54
6031281 54
6031724 54
6031784 54
6052287 54
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10086051_CLSTITLES1
Titles of Most Frequently Occurring Classifications of Patents Returned
From A Search of 10086051 on November 03, 2005

6   257/676   (1 OR, 5 XR)
         Class   257 : ACTIVE SOLID-STATE DEVICES
         257/666   LEAD FRAME
         257/676   .With structure for mounting semiconductor chip
                           to lead frame (e.g., configuration of die bonding flag,
                           absence of a die bonding flag, recess for LED)

6   257/E23.179   (0 OR, 6 XR)
         Class   257 : ACTIVE SOLID-STATE DEVICES
         257/E23.176   ...For flat cards, e.g., credit cards (EPO)
         257/E23.179   .Marks applied to semiconductor devices or
                           parts, e.g., registration marks, test patterns, alignment
                           structures, wafer maps (EPO)

5   29/827   (2 OR, 3 XR)
         Class   029 : METAL WORKING
         29/592   METHOD OF MECHANICAL MANUFACTURE
         29/592.1   .Electrical device making
         29/825   ..Conductor or circuit manufacturing
         29/827   ...Beam lead frame or beam lead device

5   257/666   (2 OR, 3 XR)
         Class   257 : ACTIVE SOLID-STATE DEVICES
         257/666   LEAD FRAME

5   257/778   (2 OR, 3 XR)
         Class   257 : ACTIVE SOLID-STATE DEVICES
         257/734   COMBINED WITH ELECTRICAL CONTACT OR LEAD
         257/778   .Flip chip

5   257/E23.037   (0 OR, 5 XR)
         Class   257 : ACTIVE SOLID-STATE DEVICES
         257/E23.001   PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                           SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
         257/E23.01   .Arrangements for conducting electric current
                           to or from solid-state body in operation, e.g., leads,
                           terminal arrangements (EPO)
         257/E23.023   ..Consisting of soldered or bonded
                           constructions (EPO)
         257/E23.031   ...Lead frames or other flat leads (EPO)
         257/E23.037   ....Characterized by die pad (EPO)

4   257/48   (4 OR, 0 XR)
         Class   257 : ACTIVE SOLID-STATE DEVICES
         257/48   TEST OR CALIBRATION STRUCTURE

4   382/145   (4 OR, 0 XR)
         Class   382 : IMAGE ANALYSIS
         382/100   APPLICATIONS
         382/141   .Manufacturing or product inspection
         382/145   ..Inspection of semiconductor device or printed
                           circuit board

4   702/187   (0 OR, 4 XR)
         Class   702 : DATA PROCESSING: MEASURING, CALIBRATING, OR
                           TESTING
         702/127   MEASUREMENT SYSTEM
         702/187   .History logging or time stamping

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3  257/787       (0 OR, 3 XR)
       Class   257 :  ACTIVE SOLID-STATE DEVICES
       257/787         ENCAPSULATED

3  257/E23.004   (0 OR, 3 XR)
       Class   257 :  ACTIVE SOLID-STATE DEVICES
       257/E23.001    PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                         SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
       257/E23.003    .Mountings, e.g., nondetachable insulating
                         substrates (EPO)
       257/E23.004    ..Characterized by shape (EPO)

3  257/E23.043   (0 OR, 3 XR)
       Class   257 :  ACTIVE SOLID-STATE DEVICES
       257/E23.001    PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                         SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
       257/E23.01     .Arrangements for conducting electric current
                         to or from solid-state body in operation, e.g., leads,
                         terminal arrangements (EPO)
       257/E23.023    ..Consisting of soldered or bonded
                         constructions  (EPO)
       257/E23.031    ...Lead frames or other flat leads (EPO)
       257/E23.043    ....Geometry of lead frame (EPO)

3  257/E23.067   (0 OR, 3 XR)
       Class   257 :  ACTIVE SOLID-STATE DEVICES
       257/E23.001    PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                         SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
       257/E23.01     .Arrangements for conducting electric current
                         to or from solid-state body in operation, e.g., leads,
                         terminal arrangements (EPO)
       257/E23.023    ..Consisting of soldered or bonded
                         constructions  (EPO)
       257/E23.06     ...Leads, i.e., metallizations or lead frames
                         on insulating substrates, e.g., chip carriers (EPO)
       257/E23.067    ....Via connections through substrates, e.g.,
                         pins going through substrate, coaxial cables (EPO)

3  438/123       (0 OR, 3 XR)
       Class   438 :  SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

       438/106         PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING,
                         ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR
       438/121         .Metallic housing or support
       438/123         ..Lead frame

3  438/14        (0 OR, 3 XR)
       Class   438 :  SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

       438/14          WITH MEASURING OR TESTING

3  438/18        (1 OR, 2 XR)
       Class   438 :  SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

       438/14          WITH MEASURING OR TESTING
       438/17          .Electrical characteristic sensed
       438/18          ..Utilizing integral test element

2  29/566.3      (1 OR, 1 XR)
       Class   029 :  METAL WORKING
       29/33R          PLURAL DIVERSE MANUFACTURING APPARATUS
                         INCLUDING MEANS FOR METAL SHAPING OR ASSEMBLING
       29/566          .Including composite tool
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      29/566.1        ..Including severing means
      29/566.3        ...To trim electric component

2   29/740        (0 OR, 2 XR)
      Class   029 :  METAL WORKING
      29/700          MEANS TO ASSEMBLE OR DISASSEMBLE
      29/729          .Means to assemble electrical device
      29/739          ..Means to fasten electrical component to
                          wiring board, base, or substrate
      29/740          ...Chip component

2   29/840        (1 OR, 1 XR)
      Class   029 :  METAL WORKING
      29/592          METHOD OF MECHANICAL MANUFACTURE
      29/592.1        .Electrical device making
      29/825          ..Conductor or circuit manufacturing
      29/829          ...On flat or curved insulated base, e.g.,
                          printed circuit, etc.
      29/832          ....Assembling to base an electrical component,
                          e.g., capacitor, etc.
      29/840          .....By metal fusion

2   29/841        (1 OR, 1 XR)
      Class   029 :  METAL WORKING
      29/592          METHOD OF MECHANICAL MANUFACTURE
      29/592.1        .Electrical device making
      29/825          ..Conductor or circuit manufacturing
      29/829          ...On flat or curved insulated base, e.g.,
                          printed circuit, etc.
      29/832          ....Assembling to base an electrical component,
                          e.g., capacitor, etc.
      29/841          .....With encapsulating, e.g., potting, etc.

2   156/64         (1 OR, 1 XR)
      Class   156 :  ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL
                        MANUFACTURE
      156/1           METHODS
      156/60          .Surface bonding and/or assembly therefor
      156/64          ..With measuring, testing, or inspecting

2   174/52.2       (1 OR, 1 XR)
      Class   174 :  ELECTRICITY:  CONDUCTORS AND INSULATORS
      174/50           BOXES AND HOUSINGS
      174/52.1         .With electric device or mounting means
                          therefor
      174/52.2         ..Potted or encapsulated

2   257/673        (0 OR, 2 XR)
      Class   257 :  ACTIVE SOLID-STATE DEVICES
      257/666          LEAD FRAME
      257/673          .With bumps on ends of lead fingers to connect
                          to semiconductor

2   257/737        (0 OR, 2 XR)
      Class   257 :  ACTIVE SOLID-STATE DEVICES
      257/734          COMBINED WITH ELECTRICAL CONTACT OR LEAD
      257/737          .Bump leads

2   257/758        (1 OR, 1 XR)
      Class   257 :  ACTIVE SOLID-STATE DEVICES
      257/734          COMBINED WITH ELECTRICAL CONTACT OR LEAD
      257/741          .Of specified material other than unalloyed
                          aluminum
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         257/750      ..Layered
         257/758      ...Multiple metal levels on semiconductor,
                         separated by insulating layer (e.g., multiple level
                         metallization for integrated circuit)

 2  257/E21.505   (O OR, 2 XR)
         Class  257 :  ACTIVE SOLID-STATE DEVICES
         257/E21.001   PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE
                            OR TREATMENT OF SEMICONDUCTOR OR SOLID-STATE DEVICES
OR OF
                        PARTS THEREOF (EPO)
         257/E21.002   .Manufacture or treatment of semiconductor
                         device (EPO)
         257/E21.04    ..Device having at least one potential-jump
                         barrier or surface barrier, e.g., PN junction,
depletion
                         layer, carrier concentration layer (EPO)
         257/E21.499   ...Assembling semiconductor devices, e.g.,
                         packaging , including mounting, encapsulating, or
treatment
                         of packaged semiconductor (EPO)
         257/E21.505   ....Insulative mounting semiconductor device on
                         support (EPO)

 2  257/E21.525   (O OR, 2 XR)
         Class  257 :  ACTIVE SOLID-STATE DEVICES
         257/E21.515   .....Involving use of mechanical auxiliary part
                         without  use of alloying or soldering process, e.g.,
                         pressure contacts (EPO)
         257/E21.521   .Testing or measuring during manufacture or
                         treatment or reliability measurement, i.e., testing of
                         parts followed by no processing which modifies  parts as
                         such (EPO)
         257/E21.525   ..Procedures, i.e., sequence of activities
                         consisting of  plurality of measurement and correction,
                         marking or sorting steps (EPO)

 2  257/E23.038   (O OR, 2 XR)
         Class  257 :  ACTIVE SOLID-STATE DEVICES
         257/E23.001   PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                            SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
         257/E23.01    .Arrangements for conducting electric current
                            to or from solid-state body in operation, e.g.,
leads,
                            terminal arrangements (EPO)
         257/E23.023   ..Consisting of soldered or bonded
                         constructions  (EPO)
         257/E23.031   ...Lead frames or other flat leads (EPO)
         257/E23.037   ....Characterized by die pad (EPO)
         257/E23.038   .....Insulative substrate being used as die
                         pad, e.g., ceramic, plastic (EPO)

 2  257/E23.046   (O OR, 2 XR)
         Class  257 :  ACTIVE SOLID-STATE DEVICES
         257/E23.001   PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                            SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
         257/E23.01    .Arrangements for conducting electric current
                            to or from solid-state body in operation, e.g.,
leads,
                            terminal arrangements (EPO)
         257/E23.023   ..Consisting of soldered or bonded
                         constructions  (EPO)
         257/E23.031   ...Lead frames or other flat leads (EPO)
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257/E23.043 ....Geometry of lead frame (EPO)
257/E23.046 .....Cross-section geometry (EPO)

2 257/E23.068 (0 OR, 2 XR)
    Class 257 : ACTIVE SOLID-STATE DEVICES
    257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                  SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
    257/E23.01 .Arrangements for conducting electric current
                  to or from solid-state body in operation, e.g., leads,
                  terminal arrangements (EPO)
    257/E23.023 ..Consisting of soldered or bonded
                  constructions (EPO)
    257/E23.06 ...Leads, i.e., metallizations or lead frames
                  on insulating substrates, e.g., chip carriers (EPO)
    257/E23.068 ....Additional leads joined to metallizations
                  on insulating substrate, e.g., pins, bumps, wires, flat
                  leads (EPO)

2 257/E23.125 (0 OR, 2 XR)
    Class 257 : ACTIVE SOLID-STATE DEVICES
    257/E23.113 ....Ceramic materials or glass (EPO)
    257/E23.116 .Encapsulations, e.g., encapsulating layers,
                  coatings, e.g., for protection (EPO)
    257/E23.123 ..Characterized by arrangement or shape (EPO)

    257/E23.124 ...Device being completely enclosed (EPO)
    257/E23.125 ....Substrate forming part of encapsulation
                  (EPO)

2 324/73.1 (0 OR, 2 XR)
    Class 324 : ELECTRICITY: MEASURING AND TESTING
    324/73.1 PLURAL, AUTOMATICALLY SEQUENTIAL TESTS

2 324/765 (1 OR, 1 XR)
    Class 324 : ELECTRICITY: MEASURING AND TESTING
    324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
                  ELECTRIC COMPONENTS
    324/537 .Of individual circuit component or element
    324/765 ..Test of semiconductor device

2 361/764 (0 OR, 2 XR)
    Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES

    361/600 HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE
                  ELECTRICAL COMPONENTS
    361/679 .For electronic systems and devices
    361/748 ..Printed circuit board
    361/760 ...Connection of components to board
    361/761 ....Component within printed circuit board
    361/764 .....Integrated circuit

2 438/106 (0 OR, 2 XR)
    Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

    438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING,
                  ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR

2 438/613 (0 OR, 2 XR)
    Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

    438/584 COATING WITH ELECTRICALLY OR THERMALLY
                  CONDUCTIVE MATERIAL
    438/597 .To form ohmic contact to semiconductive

                        material
     438/612   ..Forming solder contact or bonding pad
     438/613   ...Bump electrode

2 438/622   (0 OR, 2 XR)
    Class   438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

    438/584   COATING WITH ELECTRICALLY OR THERMALLY
                        CONDUCTIVE MATERIAL
    438/597   .To form ohmic contact to semiconductive
                        material
    438/618   ..Contacting multiple semiconductive regions
                        (i.e., interconnects)
    438/622   ...Multiple metal levels, separated by
                        insulating layer (i.e., multiple level metallization)

2 700/121   (1 OR, 1 XR)
    Class   700 : DATA PROCESSING: GENERIC CONTROL SYSTEMS OR
                        SPECIFIC APPLICATIONS
    700/90   SPECIFIC APPLICATION, APPARATUS OR PROCESS
    700/95   .Product assembly or manufacturing
    700/117   ..Particular manufactured product or operation

    700/121   ...Integrated circuit production or
                        semiconductor fabrication